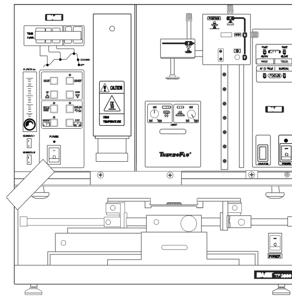
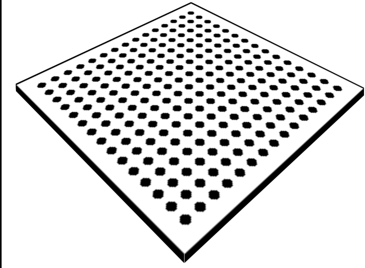
PACE®

Process Guide R-BGA-50-A

The following process can be performed with a **PACE TF 2000®**



TF 2000



BGA Component Removal

EQUIPMENT REQUIRED	PACE PART NUMBER
PACE TF 2000	6018-0115
BGA Removal Nozzle	As Applicable

OPTIONAL EQUIPMENT

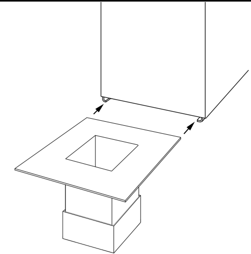
N/A

MATERIALS

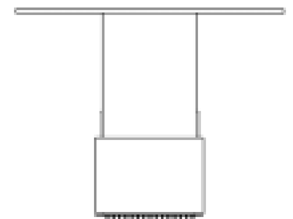
N/A

PROCEDURE

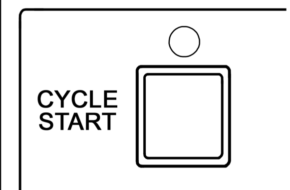
1. Select and transfer the appropriate removal profile. If a profile does not exist, see process guide G-BGA-01-A for profile development.
2. Install appropriate nozzle on the TF 2000. ①
3. Adjust board holder to accommodate the PCB and tighten as necessary.
4. Index the sliding shaft holder to the far left position under the reflow head assembly.
5. Position the component to be removed under the nozzle. ②
6. Lower the nozzle so that if possible it completely surrounds the component and is in gentle contact with the PCB surface.
7. Activate the profile cycle by depressing the "Cycle Start" button. ③
8. Approximately 10 seconds prior to the end of the cycle, activate the vacuum by depressing the vacuum button. ④
9. Upon completion of the cycle and retraction of the nozzle, immediately lift the component off the board using the vacuum wand. ⑤
10. Allow the PCB and component to cool.



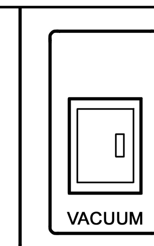
① *Install Nozzle*



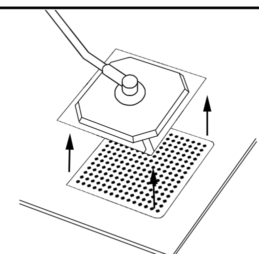
② *Position Component*



③ *Activate "Cycle Start"*



④ *Activate "Vacuum"*



⑤ *Lift Component*

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